

REMARKS

Claims 1 to 20 are currently pending in the present application. Claims 13-20 have been added. No new matter is added by the amendments.

Claims 1 and 11 are objected to as being unclear and ambiguous. These claims have been amended which should obviate this objection.

Claims 1, 2 and 10 to 12 were rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent Application Publication 2002/0048345 to Bachmann ("Bachmann"). Claims 1 and 2 include the step of providing heat to the soldering material so that portions of the soldering material flow out of the grooves in the surface of the carrier element and between the carrier element and window foil due to capillary action. Claim 10 includes the surface being inclined with a decreasing height towards an edge of the carrier element opposite to the opening, and wherein the opening is substantially free of the soldering material. Claims 11-12 include the feature of the surface having at least one groove formed therein surrounding the opening and having a portion of the soldering material therein, and wherein the opening is substantially free of the soldering material. Bachmann shows a flat surface of the carrier element and does not suggest any of the above features.

Claims 3 to 9 were rejected under 35 U.S.C. 103(a) as being unpatentable over Bachmann. Claims 3-9 depend from claim 1 and include the step of providing heat to the soldering material so that portions of the soldering material flow out of the grooves in the surface of the carrier element and between the carrier element and window foil due to capillary action. The Office Action concedes that the Bachmann surface is planar without any of these features but asserts that it would have been obvious to modify the Bachmann carrier element with the features based on improving the structural rigidity and adhesion.

Applicants respectfully point out that if increasing structural rigidity and adhesion were paramount then the structure shown in Bachmann would be utilized since this provides a uniform thickness of the soldering material. The method of claims 3-9 is directed to providing an opening that is substantially free of the soldering material. Claims 3-9 utilize portions of the soldering material flowing out of the grooves in the surface of the carrier element and between the carrier element and window foil due to capillary action to achieve the connection while maintaining the opening as substantially free of the soldering material. As such, there is no motivation to modify the structure of Bachmann using the method steps of claims 3-9 as asserted by the Office Action.

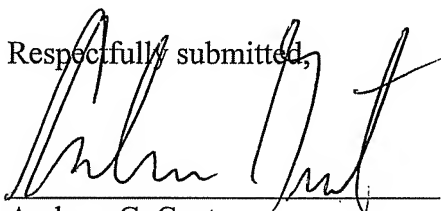
Moreover, the paragraphs 16-19 that are cited by the office action for the motivation are directed to the formation of an integral window where the window foil and carrier element are formed together from a single diamond plate and then thinned into the desired shape. In such an embodiment, Bachmann addresses any rigidity or adhesion concerns by removing the soldering step entirely. As such, claims 3-9 are patentable over Bachmann.

The newly added claims depend from claims 1, 10 or 11, respectively. As described above, claim 1 includes the step of providing heat to the soldering material so that portions of the soldering material flow out of the grooves in the surface of the carrier element and between the carrier element and window foil due to capillary action; claim 10 includes the surface being inclined with a decreasing height towards an edge of the carrier element opposite to the opening, and wherein the opening is substantially free of the soldering material; and claim 11 includes the feature of the surface having at least one groove formed therein surrounding the opening and having a portion of the soldering material therein, and wherein the opening is substantially free of the soldering material. Bachmann shows a flat surface of the carrier element and does not suggest any of the above features. The suggested motivation, even if applicable, would not lead one of ordinary skill in the art to utilize any of these features.

In view of the foregoing, Applicants respectfully submit that the specification, the drawings and all claims presented in this application are currently in condition for allowance. Accordingly, Applicants respectfully request favorable consideration and that this application be passed to allowance.

Should any changes to the claims and/or specification be deemed necessary to place the application in condition for allowance, the Examiner is respectfully requested to contact the undersigned to discuss the same.

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Respectfully submitted,


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